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Title: METHOD FOR MANUFACTURING MULTILAYER PRINTED WIRING BOARD ;  
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Inventor(s): INAGAKI YASUSHI; ICHIKAWA SHINICHIRO ;  
Applicant(s): IBIDEN CO LTD ;  
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**ABSTRACT:**

**PROBLEM TO BE SOLVED:** To provide a method for manufacturing a multilayer printed wiring board which has a conductor circuit in which a roughed surface is formed on the overall surface without undercut with a uniform thickness and in which no crack resultantly occurs in a resin insulating layer and no release occurs between the insulating layer and the circuit. **SOLUTION:** The method for manufacturing the multilayer printed circuit substrate comprises (1) a step of forming a thin film conductor layer 24 on the substrate and/or on the resin insulating layer 22, (2) a step of forming a thicker electrically plating layer 25 than the plating resist on the plating resist non-forming part after the plating resist 23 is formed by using the dry film on the part of the layer 2, (3) a step of etching the plating layer by using a first etching liquid, and (4) a step of removing the layer 24 existing under the resist 23 by using a second etching liquid after the resist 23 is removed and forming roughed surfaces on the surface of the layer 25 and the side face of the layer 24.